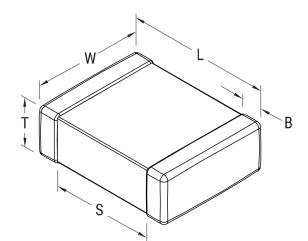


## C0603C309B3GACTU

Aliases (C0603C309B3GAC7867)

SMD Comm COG, Ceramic, 3 pF, +/-0.1 pF, 25 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 0603



Click here for the 3D model.

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.7mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information	
Series	SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	3.7 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	+/-0.1pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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